

#### Description

The NTD5865NL uses advanced trench

technology to provide excellent RDS(ON), low gate

charge and operation with gate voltages as low

as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 60V I<sub>D</sub> =50 A

 $R_{DS(ON)} < 17m\Omega @ V_{GS}=10V$ 

#### Application

Battery protection

Load switch

Uninterruptible power supply

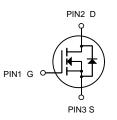
#### Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
NTD5865NL	TO-252-2L	HXY MOSFET	2500

#### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Parameter Rating	
Vds	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	tinuous Drain Current, $V_{GS}$ @ $10V^1$ 38	
Ідм	Pulsed Drain Current <sup>2</sup>	Pulsed Drain Current <sup>2</sup> 180	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	ngle Pulse Avalanche Energy <sup>3</sup> 280	
las	Avalanche Current	Avalanche Current 28	
P₀@Tc=25°C	Total Power Dissipation <sup>4</sup>	Total Power Dissipation487.7	
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R <sub>0</sub> JA	Thermal Resistance Junction-Ambient <sup>1</sup>	62	°C/W





N-Channel MOSFET



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1.0	1.5	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	13	17	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =30A	30	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	Clss		-	2498	-	PF
Output Capacitance	Coss	$V_{DS}$ =25V, $V_{GS}$ =0V,	-	185	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	80	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	12	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =30V,I <sub>D</sub> =2A,R <sub>L</sub> =1Ω	-	5.2	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{GEN}$ =3 $\Omega$	-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	27	-	nS
Total Gate Charge	Qg	N/ 201/1 201	-	36	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =30V,I <sub>D</sub> =30A,	-	9.9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	6.6	-	nC
Drain-Source Diode Characteristics	·			•		
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =30A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	58	Α
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =30A	-	35		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	47		nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

#### Notes:

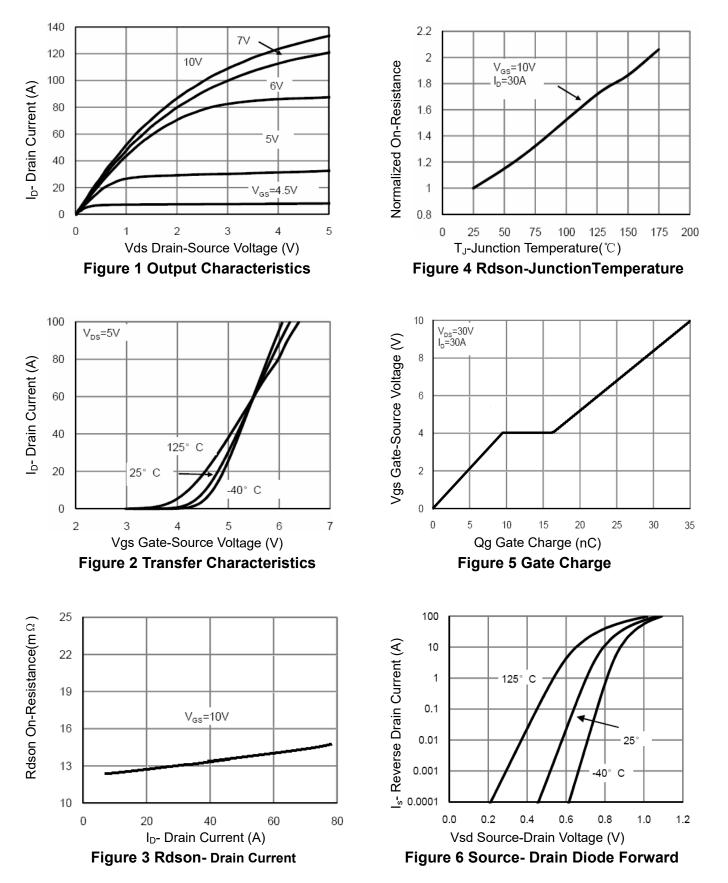
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

**2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.

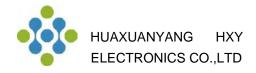
**3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

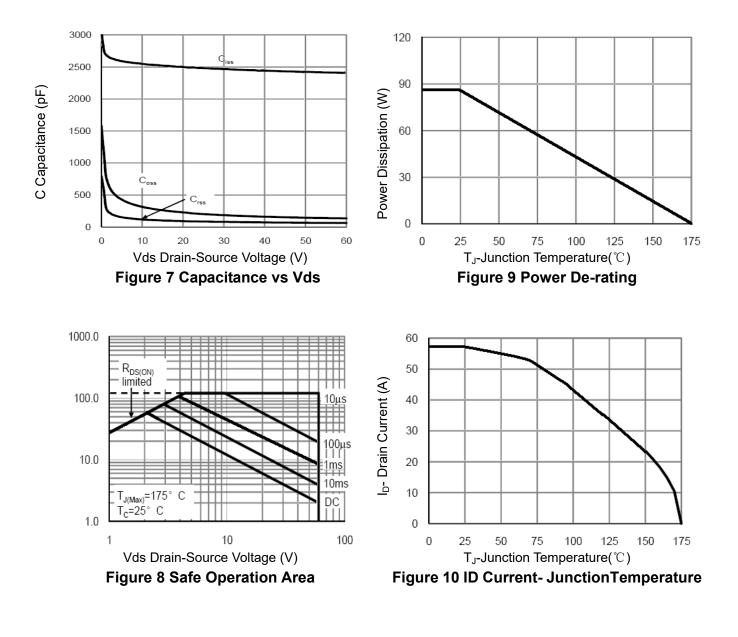
4. Guaranteed by design, not subject to production

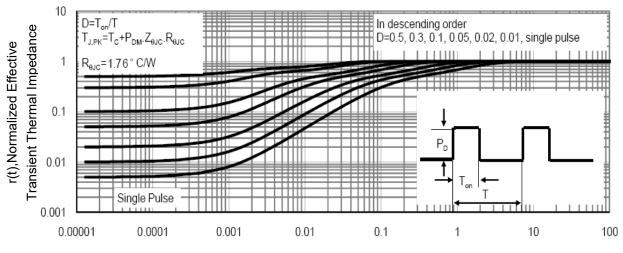
**5.**  $E_{AS}$  condition: Tj=25 °C,  $V_{DD}$ =30V,  $V_{G}$ =10V, L=0.5mH, Rg=25 $\Omega$ 

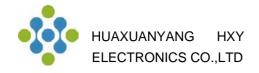


## **Typical Electrical and Thermal Characteristics (Curves)**

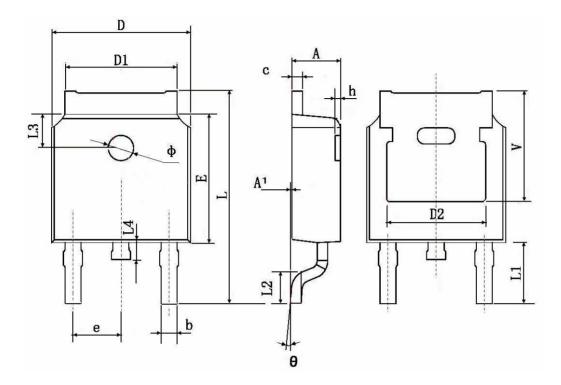








# TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0 °	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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